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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234750
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgtmc7k3f40c1n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade										
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14			
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes <sup>(4)</sup>	Yes			

### Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Snood Crada	Core Speed Grade							
Transceiver Speed Grade	C1	C2	12	13				
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_				
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes				

#### Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

## **Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	-0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	-0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	-0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	-0.5	3.9	V

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## I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/O Pin Leakage Current for Stratix V Devices (1)

Symbol	Description	Conditions	Min	Тур	Max	Unit
I	Input pin	$V_I = 0 V to V_{CCIOMAX}$	-30	_	30	μΑ
I <sub>OZ</sub>	Tri-stated I/O pin	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	-30	_	30	μΑ

### Note to Table 9:

(1) If  $V_0 = V_{CCIO}$  to  $V_{CCIOMax}$ , 100  $\mu A$  of leakage current per I/O is expected.

## **Bus Hold Specifications**

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

		Conditions	V <sub>CCIO</sub>										
Parameter	Symbol		1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μА
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0	—	-70.0		μА
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	_	120	_	160	_	200	_	300	_	500	μА
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	_	-120	_	-160	_	-200	_	-300	_	-500	μА
Bus-hold trip point	V <sub>TRIP</sub>	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

## **On-Chip Termination (OCT) Specifications**

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 1 of 2)

			Calibration Accuracy					
Symbol	Description	Conditions	<b>C</b> 1	C2,I2	C3,I3, I3YY	C4,I4	Unit	
25-Ω R <sub>S</sub>	Internal series termination with calibration (25- $\Omega$ setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%	

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			Re	,				
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%	
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%	

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} = R_{SCAL} \Big( 1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

## Notes to Equation 1:

- (1) The  $R_{OCT}$  value shows the range of OCT resistance with the variation of temperature and  $V_{CCIO}$ .
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3)  $\Delta T$  is the variation of temperature with respect to the temperature at power-up.
- (4)  $\Delta V$  is the variation of voltage with respect to the  $V_{CCIO}$  at power-up.
- (5) dR/dT is the percentage change of  $R_{SCAL}$  with temperature.
- (6) dR/dV is the percentage change of  $R_{SCAL}$  with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) (1)

Symbol	Description	Typical	Unit	
		3.0	0.0297	
	OCT variation with voltage without recalibration	2.5	0.0344	
dR/dV		1.8	0.0499	%/mV
	Todanstation	1.5	0.0744	
		1.2	0.1241	

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# **Switching Characteristics**

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

# **Transceiver Performance Specifications**

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max		
Reference Clock												
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V		2.5-V PCM HCSL	IL, Diffe	rential	LVPECL, L\	DS, and	
Sidiludius	RX reference clock pin		1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) (8)	_	40	—	710	40		710	40	_	710	MHz	
Input Reference Clock Frequency (ATX PLL) <sup>(8)</sup>	_	100		710	100		710	100	_	710	MHz	
Rise time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	_	400	_		400	_	_	400		
Fall time	Measure at ±60 mV of differential signal <sup>(26)</sup>	_	—	400	_	_	400	_	_	400	- ps	
Duty cycle	_	45	_	55	45	_	55	45	_	55	%	
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz	

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	Transceiver Speed Grade 2			nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled) (3)	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/1000/900/850 <sup>(2)</sup>			1050/1000/900/850 (2)			mV
coupled) (9)	RX reference clock pin	1.	.0/0.9/0	.85 <sup>(4)</sup>	1.	1.0/0.9/0.85 (4)			1.0/0.9/0.85 (4)		
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	_	100 ± 30%	_	Ω
chip termination resistors (21)	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
V <sub>ICM</sub> (AC and DC	$\begin{array}{c} V_{CCR\_GXB} = \\ 0.85 \text{ V or } 0.9 \\ \text{V} \\ \text{half} \\ \text{bandwidth} \end{array}$	_	600	_	_	600	_	_	600	_	mV
coupled)	V <sub>CCR_GXB</sub> = 1.0 V/1.05 V full bandwidth	_	700	_	_	700	_	_	700	_	mV
	V <sub>CCR_GXB</sub> = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t <sub>LTR</sub> (11)	_	_	_	10	_	_	10	_	_	10	μs
t <sub>LTD</sub> (12)	_	4	_		4			4		_	μs
t <sub>LTD_manual</sub> (13)	_	4	_		4	_		4	_		μs
t <sub>LTR_LTD_manual</sub> (14)	_	15	_	_	15		_	15		_	μs
Run Length	_		_	200		_	200	_		200	UI
Programmable equalization (AC Gain) <sup>(10)</sup>	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000	_	14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Currented Date	L=4	4000	_	7050	4000	_	6600	4000		6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Ç	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (16)	_			10	_		10	_		10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 <sup>(25)</sup>	600	_	3250/ 3125 <sup>(25)</sup>	600	_	3250/ 3125 <sup>(25)</sup>	Mbps
t <sub>pll_powerdown</sub> (15)	_	1	_	_	1	_	_	1	_		μs

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode <sup>(2)</sup>	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
		C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

### Notes to Table 25:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

<sup>(3)</sup> The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

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Table 27 shows the  $\ensuremath{V_{OD}}$  settings for the GX channel.

Table 27. Typical V $_{\text{OD}}$  Setting for GX Channel, TX Termination = 100  $\Omega$   $^{(2)}$ 

Symbol	V <sub>OD</sub> Setting	V <sub>op</sub> Value (mV)	V <sub>op</sub> Setting	V <sub>op</sub> Value (mV)
	0 (1)	0	32	640
	1 (1)	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
<b>V</b> op differential peak to peak	15	300	47	940
typical <sup>(3)</sup>	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

### Note to Table 27:

- (1) If TX termination resistance =  $100\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)  $^{(1)}$ 

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) <sup>(18)</sup>	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(15)</sup>	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V <sub>MAX</sub> for a receiver pin <sup>(3)</sup>	GT channels	_	_	1.2	_	_	1.2	V
Absolute V <sub>MIN</sub> for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V <sub>ID</sub> (diff p-p) before device configuration <sup>(20)</sup>	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) after device configuration (16), (20)	$V_{CCR\_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
oomiguration ', ' /	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins <sup>(4)</sup> , <sup>(20)</sup>	GX channels				(8)			

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Figure 4 shows the differential transmitter output waveform.

Figure 4. Differential Transmitter/Receiver Output/Input Waveform

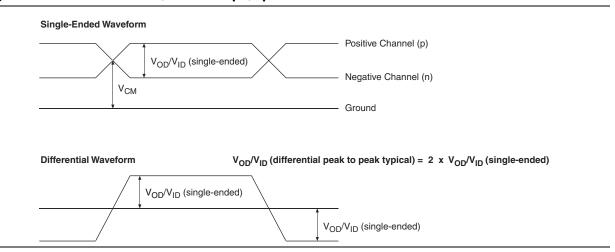


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

Figure 6 shows the Stratix V DC gain curves for GT channels.

## Figure 6. DC Gain Curves for GT Channels

## **Transceiver Characterization**

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

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Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
<b>→</b> (3) (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> ≥ 100 MHz)	_	_	0.15	UI (p-p)
t <sub>INCCJ</sub> (3), (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>OUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5 <sup>(1)</sup>	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
<b>+</b> (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>OUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ 10</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>outccj_10</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>FOUTCCJ_IO</sub>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}}$ < 100 MHz)	_	_	60	mUI (p-p)
t <sub>CASC_OUTPJ_DC</sub>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>VALUE</sub>	Numerator of Fraction	128	8388608	2147483648	_

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## **Duty Cycle Distortion (DCD) Specifications**

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C	1	C2, C2	L, I2, I2L		3, I3L, 3YY	C4	1,14	Unit
-	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

### Note to Table 44:

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# **POR Delay Specification**

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum		
Fast	4 ms	12 ms		
Standard	100 ms	300 ms		

### Note to Table 45:

# **JTAG Configuration Specifications**

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period (2)	30	_	ns
t <sub>JCP</sub>	TCK clock period (2)	167	_	ns
t <sub>JCH</sub>	TCK clock high time (2)	14	_	ns
t <sub>JCL</sub>	TCK clock low time (2)	14	_	ns
t <sub>JPSU (TDI)</sub>	TDI JTAG port setup time	2	_	ns
t <sub>JPSU (TMS)</sub>	TMS JTAG port setup time	3	_	ns

<sup>(1)</sup> The DCD numbers do not cover the core clock network.

<sup>(1)</sup> You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

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Table 46.	JTAG Timino	Parameters ar	nd Values	for Stratix V Devices
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Symbol	Description	Min	Max	Unit
t <sub>JPH</sub>	JTAG port hold time	5	_	ns
t <sub>JPCO</sub>	JTAG port clock to output	_	11 <sup>(1)</sup>	ns
t <sub>JPZX</sub>	JTAG port high impedance to valid output	_	14 <sup>(1)</sup>	ns
t <sub>JPXZ</sub>	JTAG port valid output to high impedance	_	14 <sup>(1)</sup>	ns

### Notes to Table 46:

- (1) A 1 ns adder is required for each  $V_{CCIO}$  voltage step down from 3.0 V. For example,  $t_{JPCO}$  = 12 ns if  $V_{CCIO}$  of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

# **Raw Binary File Size**

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)	
	ECCVAO	H35, F40, F35 <sup>(2)</sup>	213,798,880	562,392	
	5SGXA3	H29, F35 <sup>(3)</sup>	137,598,880	564,504	
	5SGXA4	_	213,798,880	563,672	
	5SGXA5	_	269,979,008	562,392	
	5SGXA7	_	269,979,008	562,392	
Stratix V GX	5SGXA9	_	342,742,976	700,888	
	5SGXAB	_	342,742,976	700,888	
	5SGXB5	_	270,528,640	584,344	
	5SGXB6	_	270,528,640	584,344	
	5SGXB9	_	342,742,976	700,888	
	5SGXBB	_	342,742,976	700,888	
Chrotin V CT	5SGTC5	_	269,979,008	562,392	
Stratix V GT	5SGTC7	_	269,979,008	562,392	
	5SGSD3	_	137,598,880	564,504	
	FCCCD4	F1517	213,798,880	563,672	
Ctrativ V CC	5SGSD4	_	137,598,880	564,504	
Stratix V GS	5SGSD5	_	213,798,880	563,672	
	5SGSD6	_	293,441,888	565,528	
	5SGSD8	_	293,441,888	565,528	

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Mombou		Active Serial <sup>(1)</sup>		Fast Passive Parallel (2)		
	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	D3	4	100	0.344	32	100	0.043
		4	100	0.534	32	100	0.067
GS	υ4	4	100	0.344	32	100	0.043
นอ	D5	4	100	0.534	32	100 100	0.067
	D6	4	100	0.741	32		0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
_	EB	4	100	0.857	32	100	0.107

### Notes to Table 48:

# **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

# DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
IFF XIO	Enabled	Disabled	4
	Enabled	Enabled	4

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μ\$
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(3)</sup>	μ\$
t <sub>CF2CK</sub> (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t <sub>ST2CK</sub> (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	_	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (4)	175	437	μS
t <sub>CD2CU</sub>	GOVER DOVER high to GUVERN anabled	4 × maximum	_	
	CONF_DONE high to CLKUSR enabled	DCLK period		_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(5)</sup>	_	_

### Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

# FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

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# **Active Serial Configuration Timing**

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

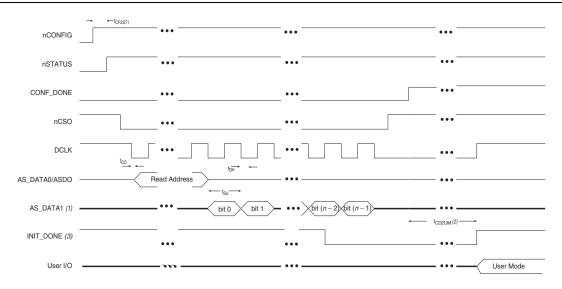
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

### Notes to Table 52:

- This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



## Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS\_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or  ${\tt CLKUSR}$  pin.
- (3) After the option bit to enable the  $INIT\_DONE$  pin is configured into the device, the  $INIT\_DONE$  goes low.

Table 53 lists the timing parameters for AS  $\times 1$  and AS  $\times 4$  configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CO</sub>	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t <sub>SU</sub>	Data setup time before falling edge on DCLK	1.5	_	ns
t <sub>H</sub>	Data hold time after falling edge on DCLK	0	_	ns

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# Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions
	V <sub>CM(DC)</sub>	DC common mode input voltage.
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V <sub>IH(AC)</sub>	High-level AC input voltage
	V <sub>IH(DC)</sub>	High-level DC input voltage
V	<b>V</b> <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V <sub>IL(AC)</sub>	Low-level AC input voltage
	V <sub>IL(DC)</sub>	Low-level DC input voltage
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.
	<b>V</b> <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V <sub>SWING</sub>	Differential input voltage
	V <sub>X</sub>	Input differential cross point voltage
	<b>V</b> <sub>OX</sub>	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
Χ		
Υ		_
Z		

Document Revision History Page 71

Table 61. Document Revision History (Part 3 of 3)

■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 2013  2.7 ■ Added Table 24, Table 48 ■ Updated Figure 9, Figure 10, Figure 11, Figure 12 ■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, TaTable 30, Table 32, Table 35 ■ Added Table 33 ■ Added "Fast Passive Parallel Configuration Timing" ■ Added "Added "Passive Serial Configuration Timing" ■ Added "Passive Serial Configuration Timing" ■ Added "Remote System Upgrades" ■ Added "Initialization" ■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 4 Table 56, and Table 59. ■ Various edits throughout to fix bugs.	
December 2012  2.5  December 2012  D	able 60
December 2012  2.6  Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46  Updated "Maximum Allowed Overshoot and Undershoot Voltage"  Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Tatable 30, Table 32, Table 35  Added Table 33  Added "Fast Passive Parallel Configuration Timing"  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Raw Binary File Size"  Added "Raw Binary File Size"  Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4  Table 56, and Table 59.	
Table 46  Updated "Maximum Allowed Overshoot and Undershoot Voltage"  Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35  Added Table 33  Added "Fast Passive Parallel Configuration Timing"  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	
Updated "Maximum Allowed Overshoot and Undershoot Voltage"  Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35  Added Table 33  Added "Fast Passive Parallel Configuration Timing"  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	Table 35,
December 2012  2.5  Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 30, Table 32, Table 35  Added Table 33  Added "Fast Passive Parallel Configuration Timing"  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7, Table 30, Table 31, Table 32, Table 38, Table 39, Table 40, Table 4, Table 56, and Table 59.	
Table 30, Table 35  Added Table 33  Added "Fast Passive Parallel Configuration Timing"  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7 Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
<ul> <li>Added "Fast Passive Parallel Configuration Timing"</li> <li>Added "Active Serial Configuration Timing"</li> <li>Added "Passive Serial Configuration Timing"</li> <li>Added "Remote System Upgrades"</li> <li>Added "User Watchdog Internal Circuitry Timing Specification"</li> <li>Added "Initialization"</li> <li>Added "Raw Binary File Size"</li> <li>Added Figure 1, Figure 2, and Figure 3.</li> <li>Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.</li> </ul>	abie 27,
December 2012  Added "Active Serial Configuration Timing"  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4  Table 56, and Table 59.	
December 2012  2.5  Added "Passive Serial Configuration Timing"  Added "Remote System Upgrades"  Added "User Watchdog Internal Circuitry Timing Specification"  Added "Initialization"  Added "Raw Binary File Size"  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
<ul> <li>Added "Passive Serial Configuration Timing"</li> <li>Added "Remote System Upgrades"</li> <li>Added "User Watchdog Internal Circuitry Timing Specification"</li> <li>Added "Initialization"</li> <li>Added "Raw Binary File Size"</li> <li>Added Figure 1, Figure 2, and Figure 3.</li> <li>Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.</li> </ul>	
<ul> <li>Added "User Watchdog Internal Circuitry Timing Specification"</li> <li>Added "Initialization"</li> <li>Added "Raw Binary File Size"</li> <li>Added Figure 1, Figure 2, and Figure 3.</li> <li>Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.</li> </ul>	
■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
June 2012  Added Figure 1, Figure 2, and Figure 3.  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 36, Table 36, Table 37, Table 38, Table 39, Table 40, Table 40, Table 56, and Table 59.	
June 2012  Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 30, Table 31, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Changed title of document to <i>Stratix V Device Datasheet</i> .	
■ Removed document from the Stratix V handbook and made it a separate document	cument.
February 2012 2.3 Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.	
December 2011 2.2 ■ Added Table 2–31.	
■ Updated Table 2–28 and Table 2–34.	
■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information at Stratix V GT devices.	out
November 2011 2.1 Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.	
■ Various edits throughout to fix SPRs.	
■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2 Table 2–24.	2–23, and
May 2011 2.0 ■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications	s" title.
■ Chapter moved to Volume 1.	
■ Minor text edits.	
■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.	
December 2010 1.1 Converted chapter to the new template.	
■ Minor text edits.	
July 2010 1.0 Initial release.	